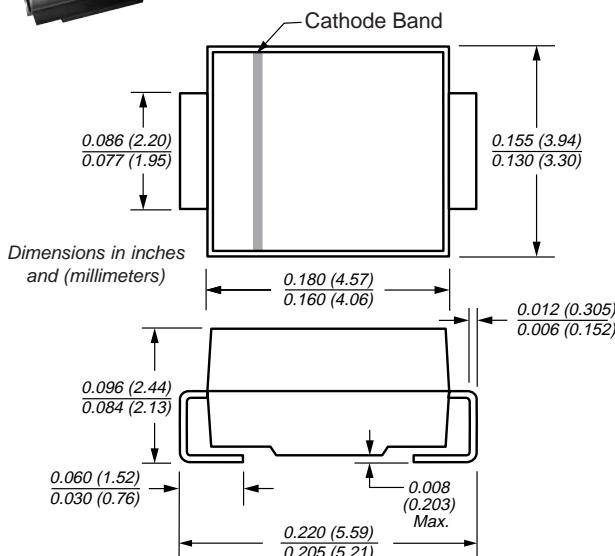
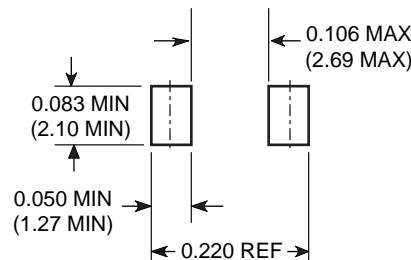




Surface Mount Schottky Rectifiers

DO-214AA (SMB)


Mounting Pad Layout



Mechanical Data

Case: JEDEC DO-214AA molded plastic body
Terminals: Solder plated, solderable per MIL-STD750, Method 2026
 High temperature soldering guaranteed:
 250°C/10 seconds at terminals
Polarity: Color band denotes cathode end
Weight: 0.003 oz., 0.093 g

Features

- Plastic package has Underwriters Laboratory Flammability Classification 94V-0
- Low profile surface mount package
- Built-in strain relief
- Low power loss, high efficiency
- For use in low voltage high frequency inverters, free wheeling, and polarity protection applications
- Guardring for overvoltage protection

Maximum Ratings and Thermal Characteristics (TA = 25°C unless otherwise noted)

Parameter	Symbol	SS22	SS23	SS24	SS25	SS26	Unit
Device marking code		S2	S3	S4	S5	S6	
Maximum repetitive peak reverse voltage	V _{RRM}	20	30	40	50	60	V
Maximum RMS voltage	V _{RMS}	14	21	28	35	42	V
Maximum DC blocking voltage	V _{DC}	20	30	40	50	60	V
Max. average forward rectified current at T _L (See Fig. 1)	I _{F(AV)}			2.0			A
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I _{FSM}			75			A
Typical thermal resistance ⁽²⁾	R _{θJA} R _{θJL}			75 17			°C/W
Operating junction temperature range	T _J		-65 to +125		-65 to +150		°C
Storage temperature range	T _{STG}			-65 to +150			°C

Electrical Characteristics (TA = 25°C unless otherwise noted)

Maximum instantaneous forward voltage at 2.0A ⁽¹⁾	V _F	0.50	0.70	V
Maximum DC reverse current ⁽¹⁾ at rated DC blocking voltage	T _A = 25°C T _A = 100°C	I _R	0.4 10	mA

Notes: (1) Pulse test: 300μs pulse width, 1% duty cycle

(2) Thermal resistance junction to lead P.C.B. mounted 0.375" (9.5mm) lead length

SS22 thru SS26



Vishay Semiconductors
formerly General Semiconductor

Ratings and Characteristic Curves ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Fig. 1 - Forward Current Derating Curve

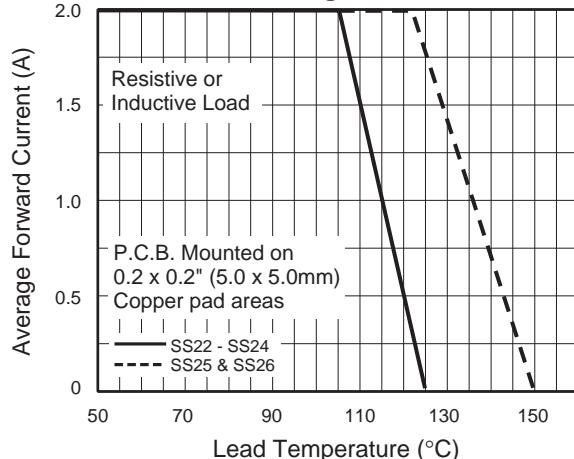


Fig. 2 - Maximum Non-repetitive Surge Current

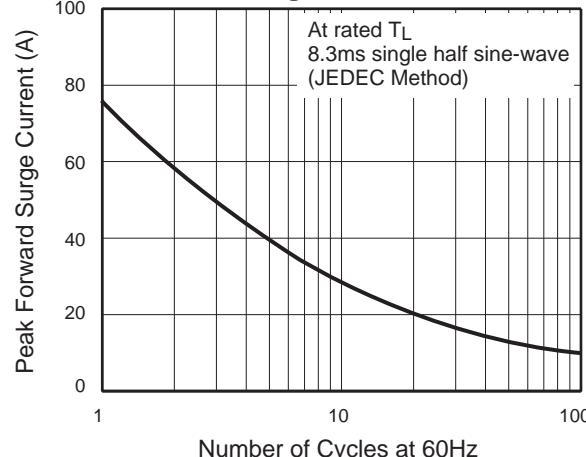


Fig. 3 - Typical Instantaneous Forward Characteristics

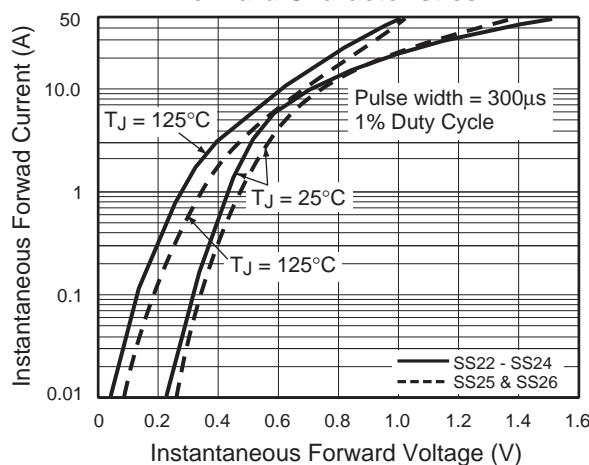


Fig. 4 - Typical Reverse Current Characteristics

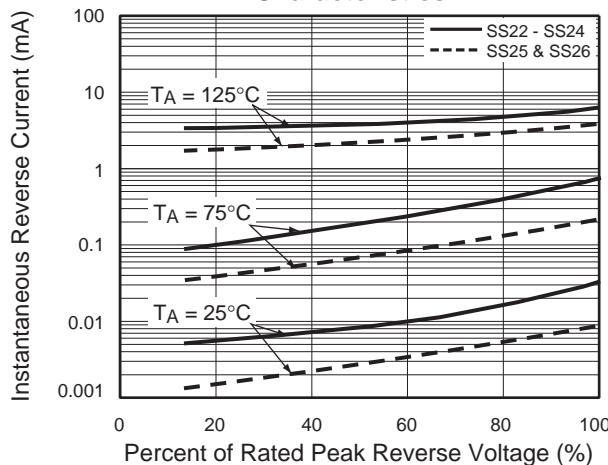


Fig. 5 - Typical Junction Capacitance

